THE OPENING ome light of the Atty. Docket No.: 203.24.02



DECLARATION FOR PATENT APPLICATION

As a below named inventor, I bareby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I sof the original, first and sole inventor (if only one name is histed below) or an original, first and joint inventor (if plural names are histed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

Method And Apparatus Of Heiding Semiconductor Wafers For Lithography And Other Wafer Processes

the specification of which (check one) __ is attached hereto or _ was filed on Angust 4, 2000 as Application Serial No. PCT/US00/21377 and was amended on Angust 14.2001

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose all information which is material to patentability as defined in Title 37, Code of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign	Application(s)	Pric Yes	rity Claimed No			
Number	Country	Day/Month	Year Filed			-
Number	Country	Day/Month	Year Filed			_
of this applica	ntion is not disclose sclose all inform the prior applica	seed in the prior Uni stion which is mater	tates Code, §120 of any United States application(s) listed below ad States application in the manner provided by the first paragraph at to patconability as defined in Title 37, Code of Federal Regulation PCT international filing date of this application: Abundoned Status: Patenned, Pending, Abundoned	of Title 35, United	States Code,	§112, Lacknowledge
Applicatio	oo Ser. No.	Filing Date	Status: Patented, Pending, Abandoned			
that these state Title 18 of th	tements were mi is United States (ide with the knowled Code and that such w	iny own knowledge are true and that all statements made on inforge that willful false statements and the like so made are punishable fillful false statements may jeopardize the validity of the application	e by fine or imprisor	nament or both	
Full name of Inventor's sig	-	oben Moffatt	19 January 2007			
Residence _		4 Washington Boul	Date Trans. Jersey City, New Jersey 07310			

1-00

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